

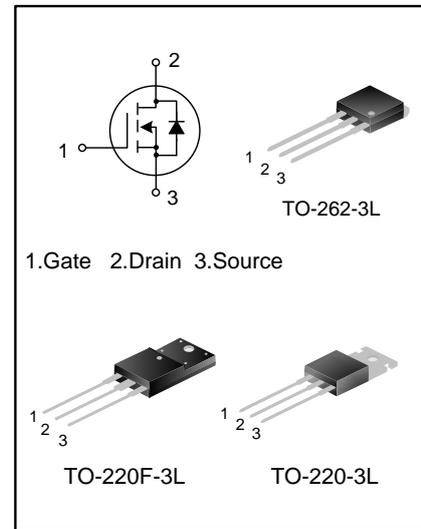
11A, 650V DP MOS POWER TRANSISTOR

DESCRIPTION

SVS11N65T/F/K is an N-channel enhancement mode high voltage power MOSFETs produced using the new platform of Silan's DP MOS technology. It achieves low conduction loss and switching losses. It leads the design engineers to their power converters with high efficiency, high power density, and superior thermal behavior. Furthermore, it's universal applicable, i.e., suitable for hard and soft switching topologies.

FEATURES

- ◆ 11A, 650V, $R_{DS(on)(typ.)}=0.37\Omega@V_{GS}=10V$
- ◆ New revolutionary high voltage technology
- ◆ Ultra low gate charge
- ◆ Periodic avalanche rated
- ◆ Extreme dv/dt rated
- ◆ High peak current capability



ORDERING INFORMATION

Part No.	Package	Marking	Material	Packing
SVS11N65T	TO-220-3L	SVS11N65T	Halogen free	Tube
SVS11N65F	TO-220F-3L	SVS11N65F	Halogen free	Tube
SVS11N65K	TO-262-3L	SVS11N65K	Halogen free	Tube

ABSOLUTE MAXIMUM RATINGS (Unless otherwise noted, $T_C=25^\circ\text{C}$)

Characteristics	Symbol	Ratings			Unit
		SVS11N65T	SVS11N65F	SVS11N65K	
Drain-Source Voltage	V_{DS}	650			V
Gate-Source Voltage	V_{GS}	± 30			V
Drain Current	$T_C=25^\circ\text{C}$	11			A
	$T_C=100^\circ\text{C}$	6.7			
Drain Current Pulsed	I_{DM}	44			A
Power Dissipation ($T_C=25^\circ\text{C}$) - Derate above 25°C	P_D	86	23	79	W
		0.69	0.18	0.63	W/ $^\circ\text{C}$
Single Pulsed Avalanche Energy (Note 1)	E_{AS}	250			mJ
Operation Junction Temperature Range	T_J	-55~+150			$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55~+150			$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristics	Symbol	Ratings			Unit
		SVS11N65T	SVS11N65F	SVS11N65K	
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.45	5.43	1.58	$^{\circ}\text{C/W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5			$^{\circ}\text{C/W}$

ELECTRICAL CHARACTERISTICS (Unless otherwise noted, $T_c=25^{\circ}\text{C}$)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain -Source Breakdown Voltage	B_{VDSS}	$V_{GS}=0V, I_D=250\mu A$	650	--	--	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=650V, V_{GS}=0V$	--	--	1.0	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 30V, V_{DS}=0V$	--	--	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2.0	--	4.0	V
Static Drain- Source On State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=5.5A$	--	0.37	0.44	Ω
Input Capacitance	C_{iss}	$f=1\text{MHz}, V_{GS}=0V, V_{DS}=100V$	--	661	--	pF
Output Capacitance	C_{oss}		--	39.7	--	
Reverse Transfer Capacitance	C_{rss}		--	3.49	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=325V, V_{GS}=10V, R_G=10\Omega, I_D=11A$ (Note 2,3)	--	14	--	ns
Turn-on Rise Time	t_r		--	33.4	--	
Turn-off Delay Time	$t_{d(off)}$		--	54.4	--	
Turn-off Fall Time	t_f		--	30.2	--	
Total Gate Charge	Q_g	$V_{DD}=520V, V_{GS}=10V, I_D=11A$ (Note 2,3)	--	23.52	--	nC
Gate-Source Charge	Q_{gs}		--	4.36	--	
Gate-Drain Charge	Q_{gd}		--	12.14	--	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_S	Integral Reverse P-N Junction Diode in the MOSFET	--	--	11	A
Pulsed Source Current	I_{SM}		--	--	44	
Diode Forward Voltage	V_{SD}	$I_S=11A, V_{GS}=0V$	--	--	1.4	V
Reverse Recovery Time	T_{rr}	$I_S=11A, V_{GS}=0V, dI_F/dt=100A/\mu s$	--	331	--	ns
Reverse Recovery Charge	Q_{rr}		--	4	--	μC

Notes:

- $L=30\text{mH}, I_{AS}=3.8A, V_{DD}=100V, R_G=25\Omega$, starting $T_J=25^{\circ}\text{C}$;
- Pulse Test: Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$;
- Essentially independent of operating temperature.

TYPICAL CHARACTERISTICS

Figure 1. On-Region Characteristics

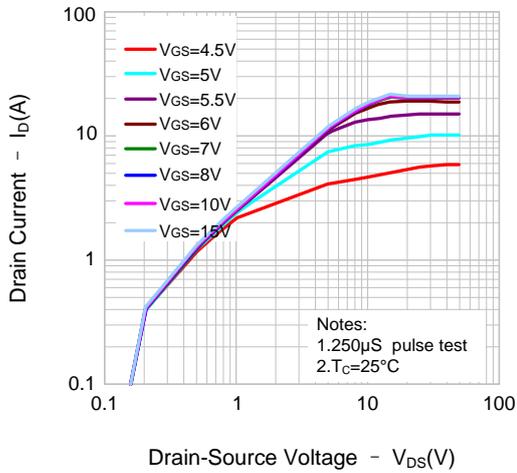


Figure 2. Transfer Characteristics

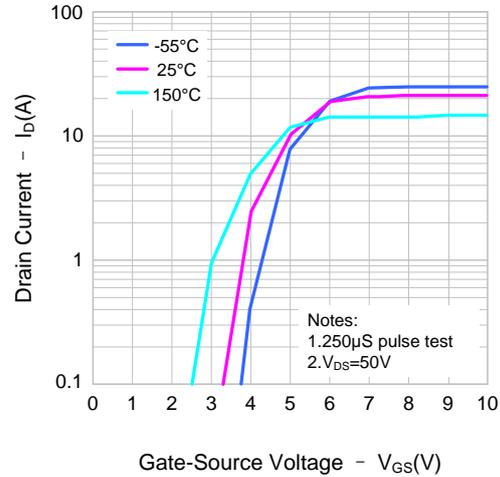


Figure 3. On-Resistance vs. Drain Current

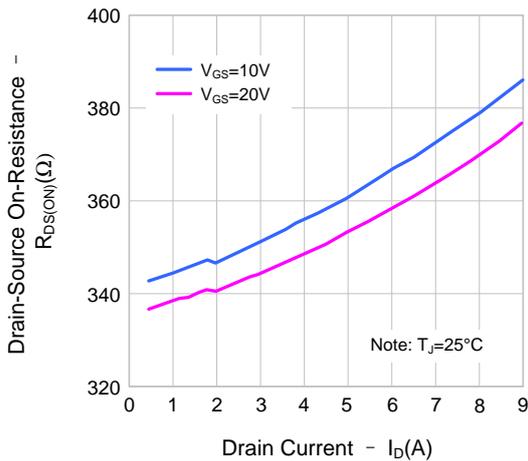


Figure 4. Body Diode Forward Voltage vs. Source Current and Temperature

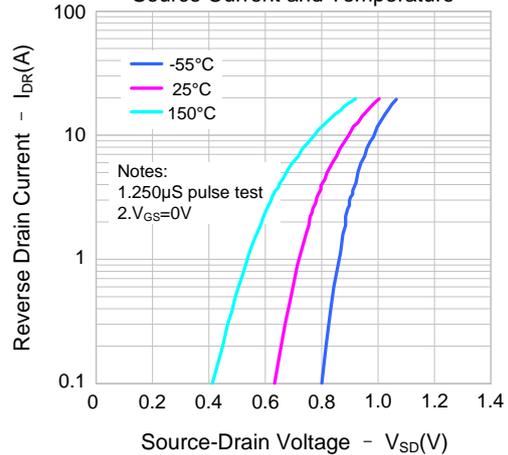


Figure 5. Capacitance Characteristics

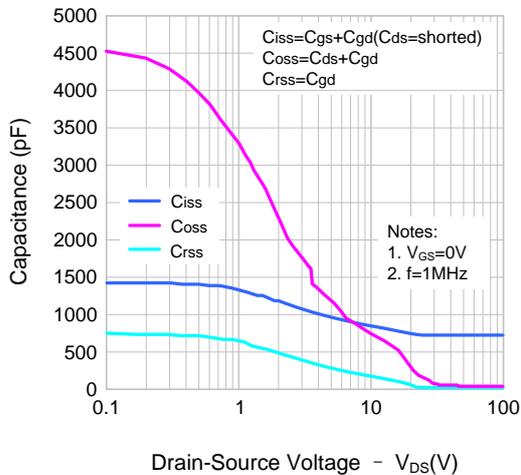
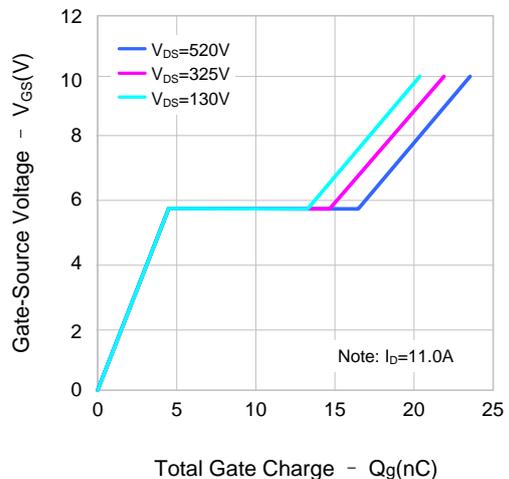


Figure 6. Gate Charge Characteristics



TYPICAL CHARACTERISTICS (continued)

Figure 7. Breakdown Voltage vs. Temperature

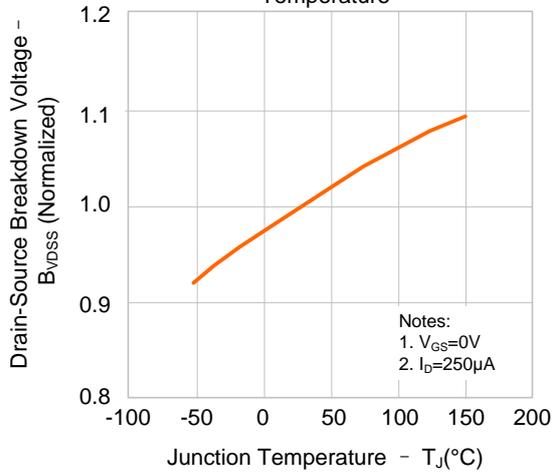


Figure 8. On-Resistance vs. Temperature

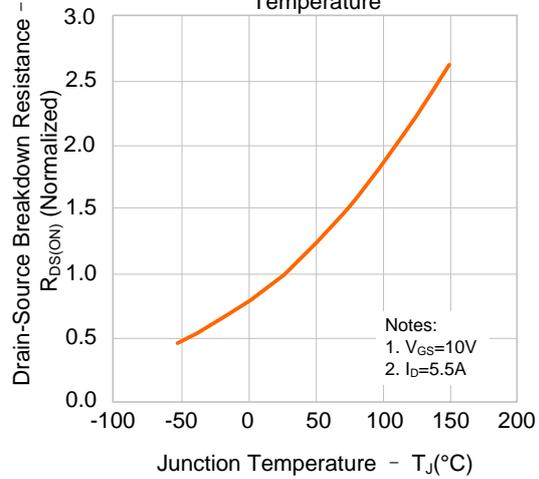


Figure 9-1. Max. Safe Operating Area (SVS11N65T)

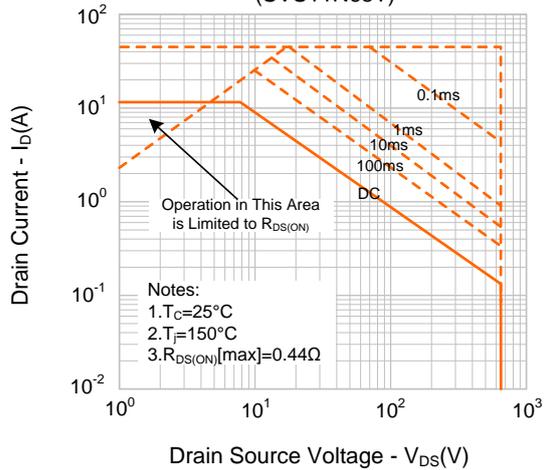


Figure 9-2. Max. Safe Operating Area (SVS11N65F)

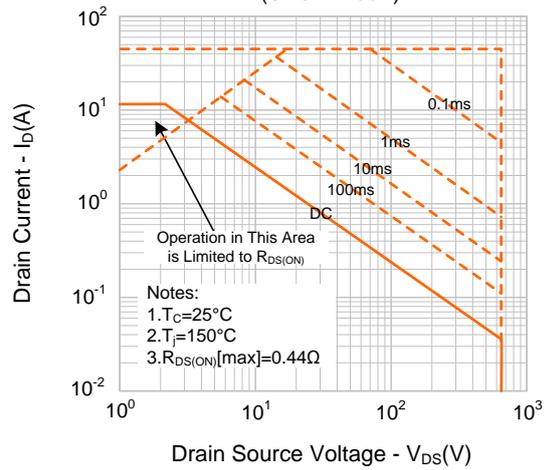
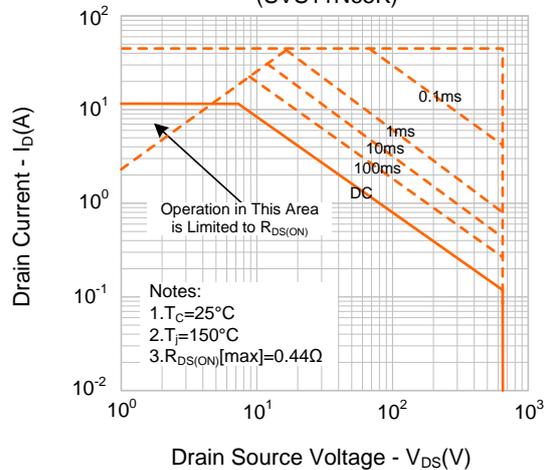
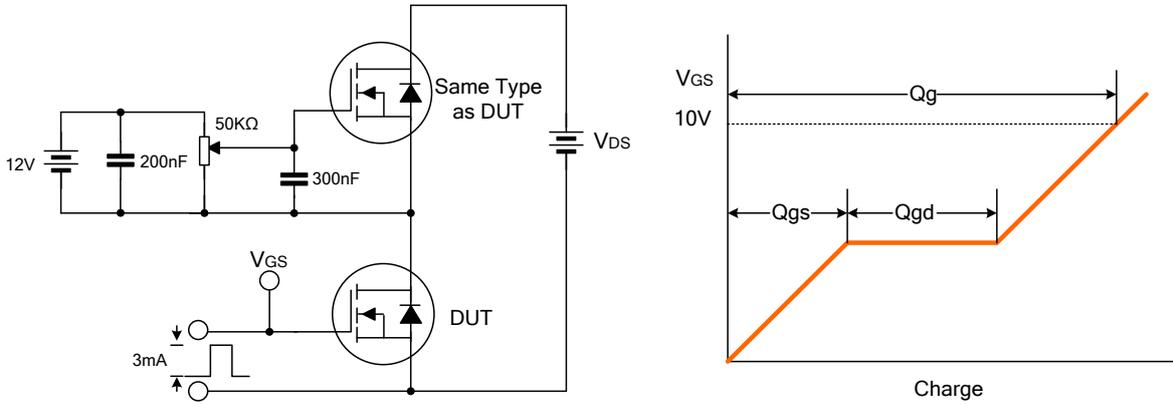


Figure 9-3. Max. Safe Operating Area (SVS11N65K)

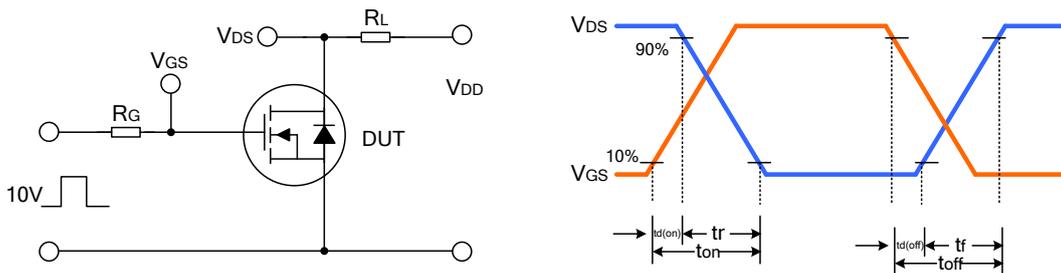


TYPICAL TEST CIRCUIT

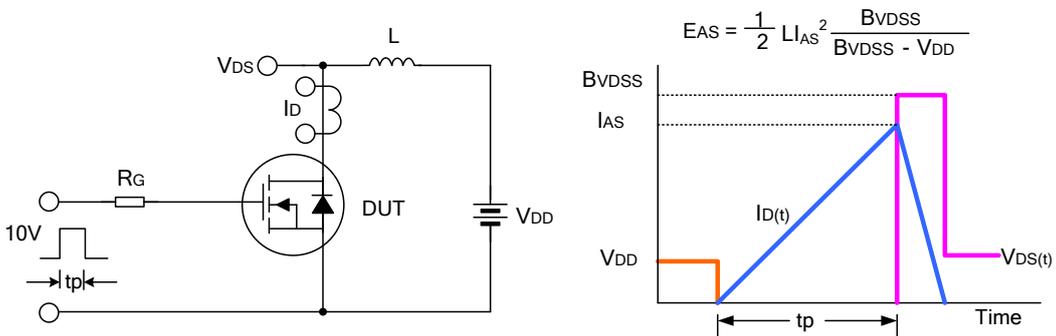
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



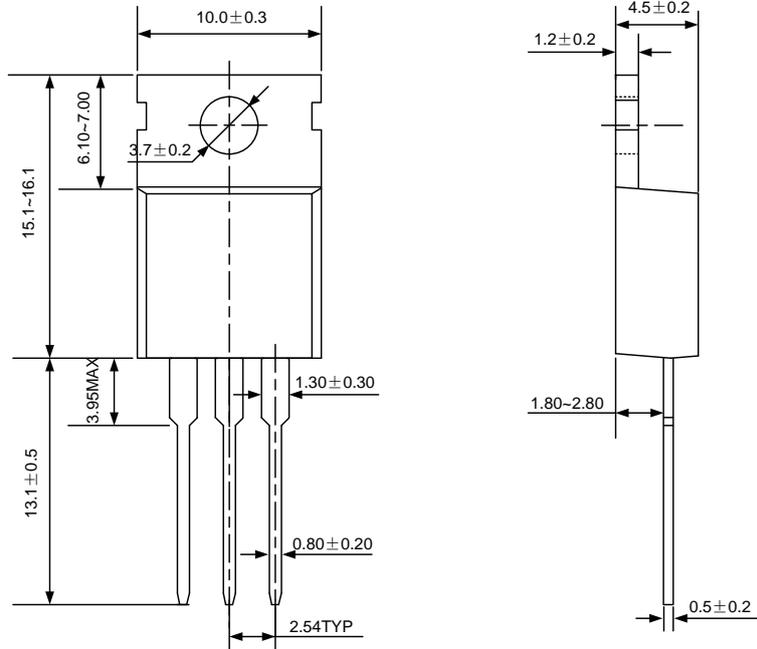
Unclamped Inductive Switching Test Circuit & Waveform



PACKAGE OUTLINE

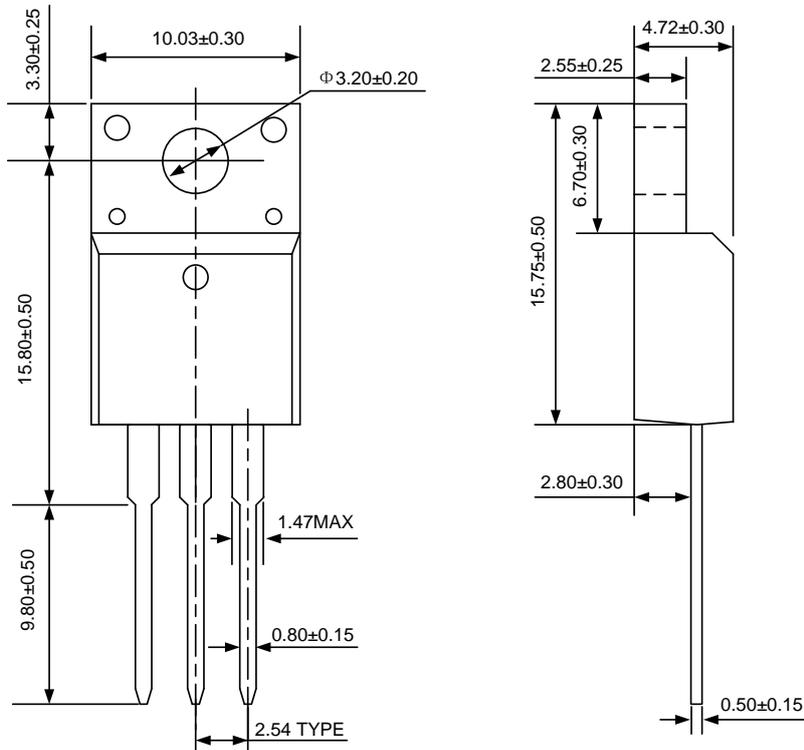
TO-220-3L

UNIT: mm

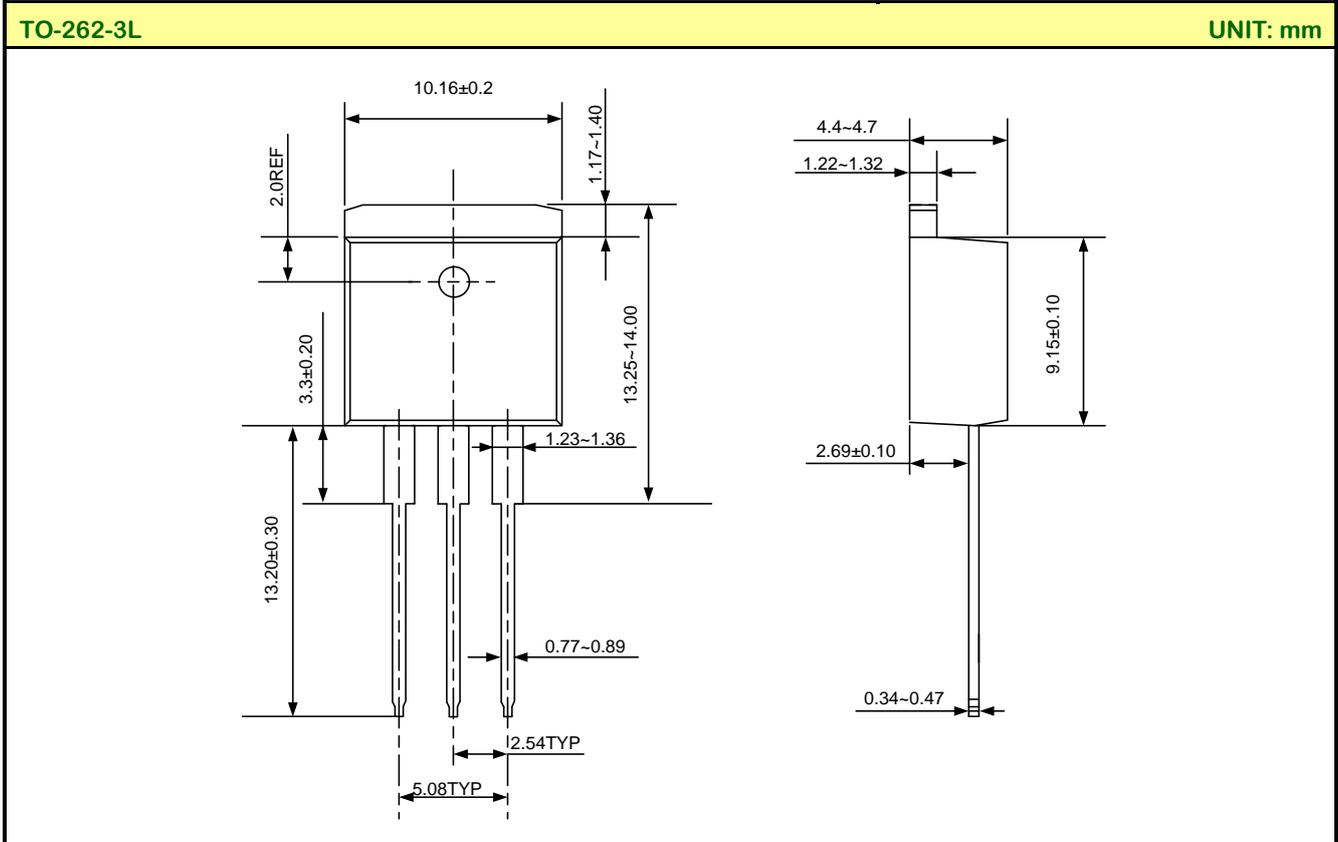


TO-220F-3L

UNIT: mm



PACKAGE OUTLINE



Disclaimer :

- Silan reserves the right to make changes to the information herein for the improvement of the design and performance without further notice! Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current.
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- Silan will supply the best possible product for customers!

Part No.:	SVS11N65T/F/K	Document Type:	Datasheet
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Rev.:	1.2	Author:	Yin Zi
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Revision History:

1. Modify the thermal characteristics
2. Modify the Q value

Rev.:	1.1	Author:	Yin Zi
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Revision History:

1. Modify the value of $R_{DS(ON)}$

Rev.:	1.0	Author:	Yin Zi
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Revision History:

1. First release
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